

S/N 10/722,838

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant:	Suan J. Boon	Examiner:	James Mitchell
Serial No.:	10/722,838	Group Art Unit:	2813
Filed:	November 26, 2003	Docket No.:	303.601US3
Customer No.:	73115	Confirmation No.:	8165
Title: METHOD OF PACKAGING AT A WAFER LEVEL USING AN ADHESIVE (as <u>amended</u> )			

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**AMENDMENT & RESPONSE UNDER 37 C.F.R. § 1.111**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

In response to the Office Action mailed June 27, 2008, please amend the application as follows: